

D 应达利电子INTERQUIP ELECTRONICS

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		-				<u> </u>		
	C	Custo	ome	er A	<b>bb</b>	rova	al S	heets
		Product	t:	Crys	stal Res	onator		
		Description:		SMO	SMCE2520 4pads			
	IQG P/N:		5ZA	5ZAA12000183KFA5Q3 VER: 0.1				
		Ref No:						
		Custom	ier P/N	1:				
	Appro	val Secti	ion:					
	Date:							
	Custo	mer					Attn:	
	DEPT.		DEPT.		DEPT.		DEPT.	
		Prepare	d by:	Checke	ed by:	Approv	ed by:	
		Ange	la Li					
		2021/-	4/20					
					KAS NAFEMINT 0005	SGS	UKAS MAXACCHINY SYSTEMS 0005	RoHS
	IQL has been certified for the above management systems.							
Note 1:	Note 1: It is prohibited to use the "Environment-related Substances to be Controlled" in level 1 in Sony GP system. The resin ink, paint and cable used in molded products must be purchased from the suppliers in the Sony GP supplier list							
Note 2:	Note 2: Not suitable for ultrasonic welding. ultrasonic welding to other specifications							



# **贝** 应达利电子INTERQUIP ELECTRONICS

Description: SMCE2520 4pads IQG P/N:

5ZAA12000183KFA5Q3

Rev	Revise page	Revise contents	Date	Reviser
0	N/A	Initial released		

## ☑ 应达利电子INTERQUIP ELECTRONICS

Description: SMCE2520 4pads IQG P/N: 5ZAA12000183KFA5Q3

## **Specification**

PART NO 5ZAA12000183KFA5Q3

- 1. Scope:
- 1.1 This specification applies to the RoHS/SONY compliance quartz crystal unit with a frequency of 12MHz which will be used in crystal oscillator applications.
- 2. Construction:
- 2.1 Type of Quartz Resonator: SMCE2520 4pads

#### 3. **Electrical Characteristics**

3.1	Nominal Frequen	12,000,000	Hz		
3.2	Load Capacitance	18pF			
3.3	Frequency Tolera	± 30ppm			
3.4	Frequency Tempe	±30ppm			
3.5	Resonance Resis	150ohms Max			
3.6	Osc mode:	Fundamental mode			
3.7	Shunt Capacitance	e(C <sub>0</sub> ):	<2pF		
3.8	Drive Level(D <sub>L</sub> ):	< 50µW			
3.9	Operating Tempe	-20 to + 70°C			
3.10	Storage Tempera	-55 to + 125°C			
3.11	Insulation Resista	>500 M ohms			
3.12	$Aging( \triangle f_A):$		± 3ppm per Ye	ar	
3.13	Marking:	Q+DateCode+LotCode+12.000	)		
3.14	OTHERS:	Not recommended for safety ap	oplications		



Description: SMCE2520 4pads

IQG P/N: 5ZAA12000183KFA5Q3

## 4. Reliability Specifications

This is the quality control and quality assurance and reliability tests performance data for the

RoHS/SONY compliance 12MHz SMCE2520 4pads crystal resonators (P/N.: 5ZAA12000183KFA5Q3)

related to the specification and approval sheet provided by INTERQUIP ELECTRONICS CO., LTD .

Standard test condition (TEMP.: 20±5°C. Relative humidity: 65±20%)

For any discrepancy in GO/NG, test will be done at TEMP.25±2°C, R.H. 65±5%.

NO.	PROCESS	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3- 2006, Method Cab)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 96 hrs at 40 °C $\pm$ 3 °C, with 93 %R.H, Then keep the DUT in dry oven at 40 $\pm$ 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours.
4.5	Vibration (GB/T 2423.10- 1995, Method Fc)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Apply 0.75mm vibration at sweep frequency $10\sim$ 500 Hz, 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.and exhibit no visible damage.	Peak 1000m/s2, normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.and exhibit no visible damage.	Free drop to the steel plate with thickness of 3 mm from 1.00 m heights for 3 times.
4.8	Solderability (IEC60068-2- 58,Test Td:)	Terminals shall be covered more then 95% with solder.	Passed through the re-flow oven under the following condition. Preheat 150 to $180^{\circ}$ C for 60 to $120$ sec, and soldering time for $20s \pm 5s$ at $235^{\circ}$ C, peak soldering time for $10s \pm 1s$ betweein 240 and 250°C. There is no need to do functional test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C- 6429 Method 1 & 2 )	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 1.8kg for at least 60 seconds.
4.10	Resistance to Soldering Heat (IEC60068-2-58,Test Td: Table 4)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and sodering time for 60s max at 235° C, peak soldering time for 20s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours.
4,11	OTHERS		

# D 应达利电子INTERQUIP ELECTRONICS



### EXTERNAL DIMENSIONS

DATE

MODIFY DESCRIPTION

ΒY



DWG.NO. 004-061P7-000 REV. 7

